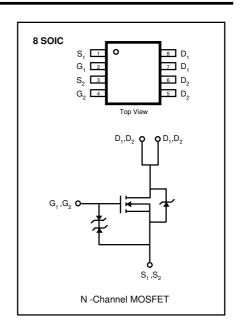
FEATURES

- $\ \ \, \square \ \ \, \text{Lower} \, \, \mathsf{R}_{\mathsf{DS}(\mathsf{on})}$
- ☐ Improved Inductive Ruggedness
- ☐ Fast Switching Times
- ☐ Low Input Capacitance
- Extended Safe Operating Area
- ☐ Improved High Temperature Reliability

Product Summary

Part Number	BV _{DSS}	R _{DS(on)}	I _D	
SSD2025	60V	0.10Ω	3.3A	



Absolute Maximum Ratings

Symbol	Characteristic	Value	Units		
V_{DSS}	Drain-to-Source Voltage	60	V		
,	Continuous Drain Current T _A =25°C	3.3	Α		
l _D	Continuous Drain Current T _A =70°C	2.6	A		
I _{DM}	Drain Current-Pulsed ①	10.0	Α		
V_{GS}	Gate-to-Source Voltage	±20	٧		
	Total Power Dissipation ($T_A=25^{\circ}C$)	2.0			
P_{D}	(T _A =70 °C)	1.3	W		
T _J , T _{STG}	Operating and Junction Storage	EE +o .1EO	J		
3 7 3 ld	Temperature Range	- 55 to +150			

Thermal Resistance

Symbol	Characteristic	Тур.	Max.	Units
R_{\ThetaJA}	Junction-to-Ambient		62.5	°C/W



$\textbf{Electrical Characteristics} \; (\textbf{T}_{\textbf{C}} = 25 \, ^{\circ} \textbf{C} \; \; \text{unless otherwise specified})$

Symbol	Characteristic	Min.	Тур.	Max.	Units	Test Condition
BV _{DSS}	Drain-Source Breakdown Voltage			-	٧	$V_{GS} = 0V, I_D = 250 \mu A$
$V_{GS(th)}$	Gate Threshold Voltage			-	٧	$V_{DS} = 5V , I_{D} = 250 \mu A$
I _{GSS}	Gate-Source Leakage, Forward			100	nA	V _{GS} =20V
GSS	Gate-Source Leakage, Reverse			-100	nA	V _{GS} =-20V
	Drain-to-Source Leakage Current			1.0	μ A	V _{DS} =48V
I _{DSS}				25		V_{DS} =48 V , T_{C} =55 $^{\circ}$ C
I _{DON}	On-State Drain-Source Current	10			Α	V _{DS} =5V ,V _{GS} =10V
_	Static Drain-Source		0.065	0.1)	$V_{GS} = 10V, I_D = 3.3A$
R _{DS(on)}	On-State Resistance ②		0.084	0.2	Ω	$V_{GS} = 4.5 V, I_D = 2.5 A$
g _{FS}	Forward Transconductance 2		7.0		S	$V_{DS} = 15V, I_{D} = 3.3A$
$t_{d(on)}$	Turn-On Delay Time		16	25		
t _r	Rise Time		18	30	no	$V_{DD} = 30V, I_{D} = 1.0A,$
$t_{d(off)}$	Turn-Off Delay Time		40	50	ns $R_0=6.0\Omega$,	
t _f	Fall Time		23	40		23
Q_g	Total Gate Charge		18	30		\/ _20\/ \/ _10\/
Q_gs	Gate-Source Charge		2.3		nC	V_{DS} =30V, V_{GS} =10V, I_{D} =3.3A ② ③
Q_{gd}	Gate-Drain ("Miller") Charge		4.7		I _D =3.3A	

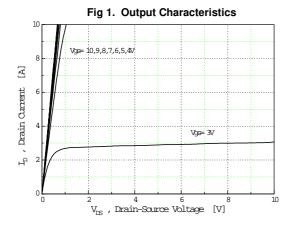
Source-Drain Diode Ratings and Characteristics

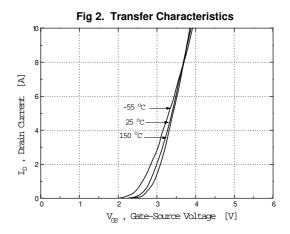
Symbol	Characteristic	Min.	Тур.	Max.	Units	Test Condition
I _S	Continuous Source Current (Body Diode)			1.7	А	Modified MOSFET Symbol Showing the Integral Reverse P-N Junction Rectifier
V _{SD}	Diode Forward Voltage ②	-	1	1.2	٧	T _A =25 °C,I _S =1.7A,V _{GS} =0V
t _{rr}	Reverse Recovery Time 2		70	100	ns	$T_A=25^{\circ}C_{,}I_F=1.7A_{,}di_F/dt=100A/\mu s$

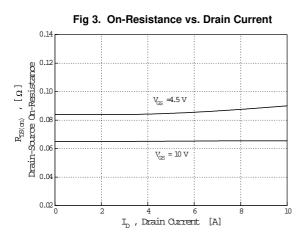
Notes;

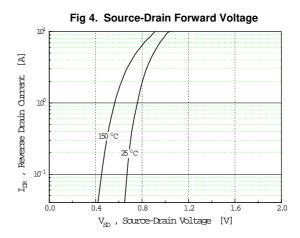
- ① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- ② Pulse Test : Pulse Width = 250 μ s, Duty Cycle \leq 2%
- 3 Essentially Independent of Operating Temperature

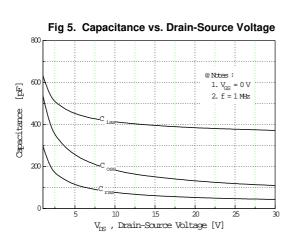


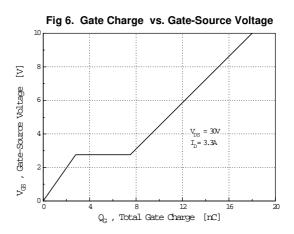




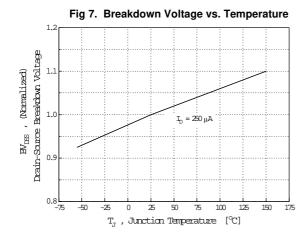












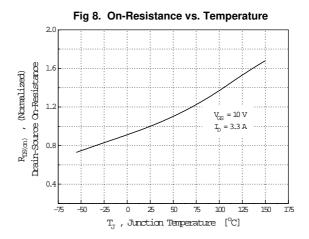
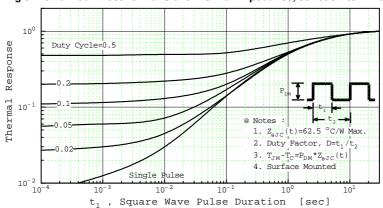


Fig 9. Nomalized Effective Transient Thermal Impedance, Junction-to-Ambient





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